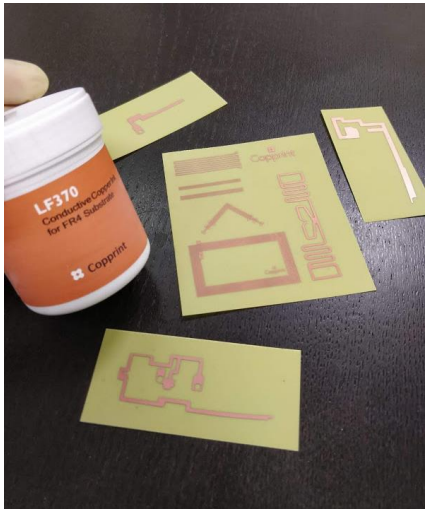


Copprint

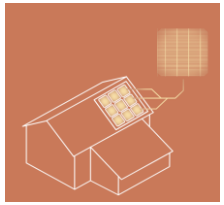
LF-370 Conductive copper ink for FR4

Best conductivity in class

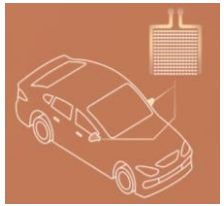
The Future of Printed Electronics is Copper.

Copprint enables very-low cost, high conductivity, sustainable printed electronics.

Three key segments:
Printed RFID antennas; Photovoltaics; Flexible electronics



Copprint Strategic Investors



Copprint Awards

Copprint

Henkel

hp

LOPEC
DRIVING THE FUTURE OF PRINTED ELECTRONICS

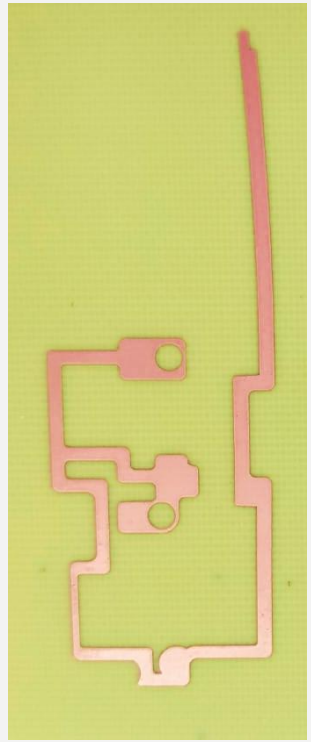
Printed Electronics EUROPE

New product: LF-370

Designed for **FR-4** substrate:

- Highest conductivity in class
- Excellent durability
- Excellent adhesion
- Simple process
- Solderable
- Hybrid ink – nano and micro copper particles.

Excellent performance also on **Alumina** and **Aluminum**



Copprint

Copper inks that outperform Silver
LF-370 – highest conductivity in class

Copprint screen-printing Nano Copper Inks for a range of substrates:

LF-300 – Paste for paper substrate - Released

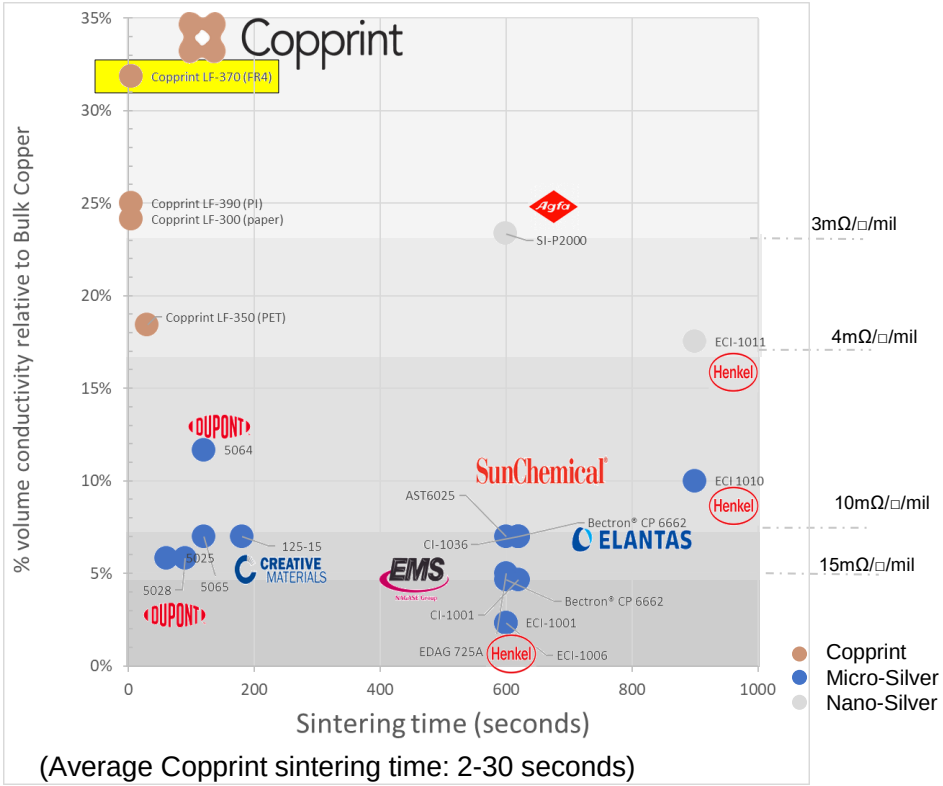
LF-350 – paste for PET substrate – Released

LF-370 – paste for FR4 substrate – Released

LF-390 – paste for PI substrate

LF-380 – paste for HJT PV cells

Additional substrates: Alumina, Glass, PC, PEN, CFRP, Tesline

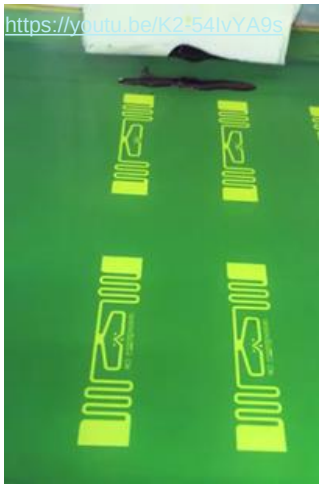


(Average Copprint sintering time: 2-30 seconds)

Copprint

Really Simple and inexpensive Fabrication

1) Print



Screen printing in few seconds

2) Dry

Drying oven/conveyor/UV 1-60 seconds

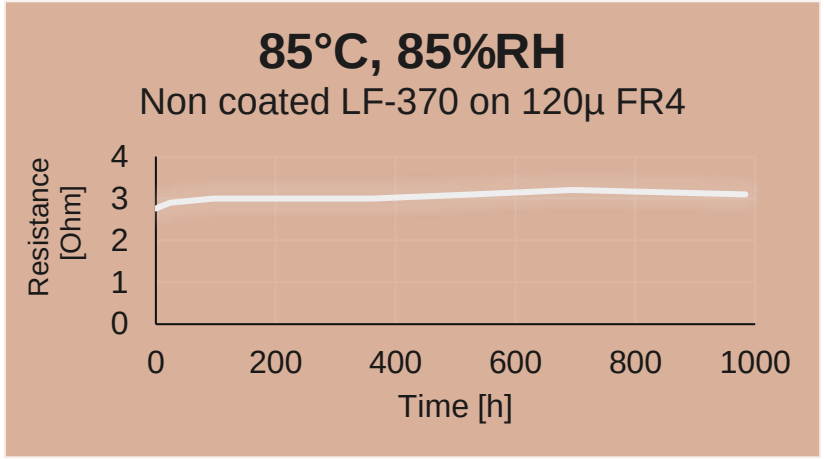
3) Sinter

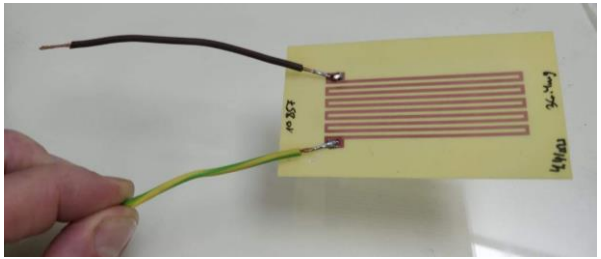
120µ FR4: few sec at 300°C – contactless laminator (Above speed 0.7meter/min - with 80cm heating elemet it is 10meter/min)
1mm FR4: 5-30 sec 280°-320°C - hotpress

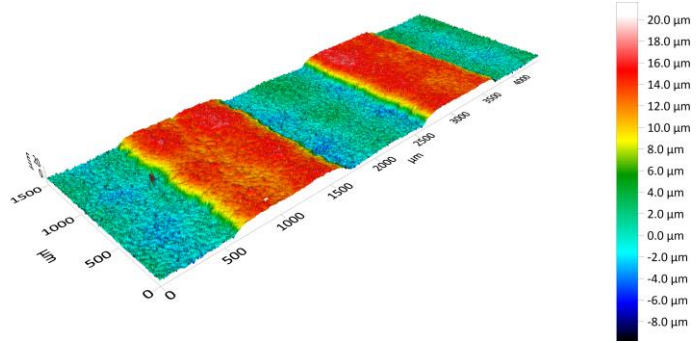
Copprint

Excellent conductivity, durability and printability

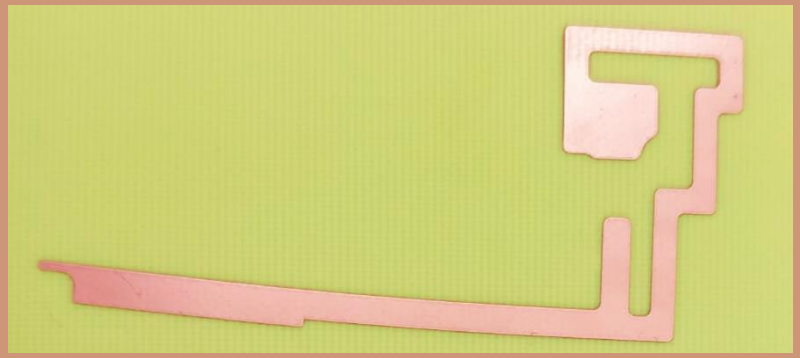
- ✓ ~2.2mΩ/□/mil
- ✓ 85-90% solids
- ✓ Excellent 85/85 performance
- ✓ Excellent adhesion
- ✓ Crosshatch test – 5b
- ✓ Solderability







Copprint



For more information visit Copprint.com or contact us at Info@Copprint.com

Copprint